



Product / Process Change Notice

No.: Z200-PCN-DM201706-01-A

Date: 06/27/2017

Change Title : W25Q257JV "J-Series" (58nm) to replace W25Q257FV "F-Series" (58nm) 256Mb 3.3V SpiFlash® Memories

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Assembly Packing Testing Others

Affected Product(s) :

W25Q257FVFIF , W25Q257FVFIG , W25Q257FVFIQ

Description of Change(s)

The W25Q257JV 256Mb SpiFlash® Memories use Winbond's 58nm Flash technology. It is function-compatible with W25Q257FV 58nm devices offering improved performance, features and availability.

Reason for Change(s) :

Improve features and Command backward compatible with W25Q257FV (same Superset Instruction Set), please refer the attachment of comparison table.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Concern (Please refer to attachment I)

Reliability : No Concern (Please refer to attachment II)

Hazardous Substances: No Concern (Please refer to attachment III)

Qualification Plan/ Results :

Based on Winbond W25Q257JV Serial Flash Reliability report, the new product meets our criteria and no quality concern (refer to attachment in details)

Implementation Plan :

Please refer to Attachment IV for details.

Date Code: ____ onward Lot No: ____ onward Proposed first ship date: Please refer attachment IV for detail

Originator: (QA)

Hyhuang

Approval: (QA Dept. Manager)

YH Cheng

Approval: (QRA Director)

Simon Chen

Contact for Questions & Concerns

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Address : # 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan
E-mail: Hyhuang8@winbond.com



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Comment:

Date: _____

Dept. name: _____

Person in charge: _____



Winbond Electronics Corporation

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Product Obsolescence Notice

W25Q257JV SpiFlash Memories

Notification Date: Jun, 26, 2017

Dear Valued Customer,

This letter is to notify you of Winbond's intention to terminate production of the W25Q257FV SpiFlash memory, and replace it with the W25Q257JV. Replacement part numbers are listed below:

Winbond Current PN (58nm F-Series)	Winbond Primary Replacement PN (58nm J-Series)
W25Q257FVFIF	W25Q257JVFIQ
W25Q257FVFIFG	
W25Q257FVFIQ	

The W25Q257JV device features:

Features

- a) Command backward compatible with W25Q257FV (same Superset Instruction Set)
- b) Clock operation up to 133MHz
- c) SPI with Single / Dual / Quad / QPI
- d) Flexible architecture with 4KB sectors

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q257FV	Jun./30/ 2017	Dec./30/ 2017	Jun./30/ 2018	W25Q257JV	Feb./24 2017	Feb./24/ 2017

Eddy Hung

Assistant Vice President of Flash Marketing